

3.0A SURFACE MOUNT SUPER-FAST RECTIFIER

FEATURES

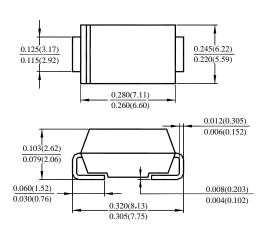
- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 100A Peak
- Ideally Suited for Automated Assembly
- Plastic Material: UL Flammability Classification Rating 94V-0

MECHANICAL DAT A

- · Case: Molded Plastic
- Terminals: Solder Plated Terminal Solderable
 Por MIL STD 202 Method 208
- per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- SMB Weight: 0.093 grams (approx.)
- SMC Weight: 0.21 grams (approx.)

 Mayarting Basition: Any
- Mounting Position: AnyMarking: Type Number

ES3A-ES3D



Dimensions in inches and (millimeters) DO-214AB (SMC)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 $^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	ES3A/B	ES3B/B	ES3C/B	ES3D/B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	150	200	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	105	140	V
Average Rectified Output Current @ T _T = 100°C	Io	3.0				Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Loa (JEDEC Method)	d I _{FSM}	100				А
Forward Voltage @ I _F = 3.0A	V _{FM}	0.9				V
Peak Reverse Current @ T _A = 25°C at Rated DC Blocking Voltage @ T _A = 125°C		10 500				μА
Reverse Recovery Time (Note 3)	t _{rr}	25				ns
Typical Junction Capacitance (Note 2)	Cj	45				pF
Typical Thermal Resistance, Junction to Terminal (Note 1)	$R_{\theta JT}$	15				K/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150				°C

Notes: 1. Unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.

- 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- 3. Measured with $I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$. See Figure 5.



ES3A-ES3D Typical Characteristics

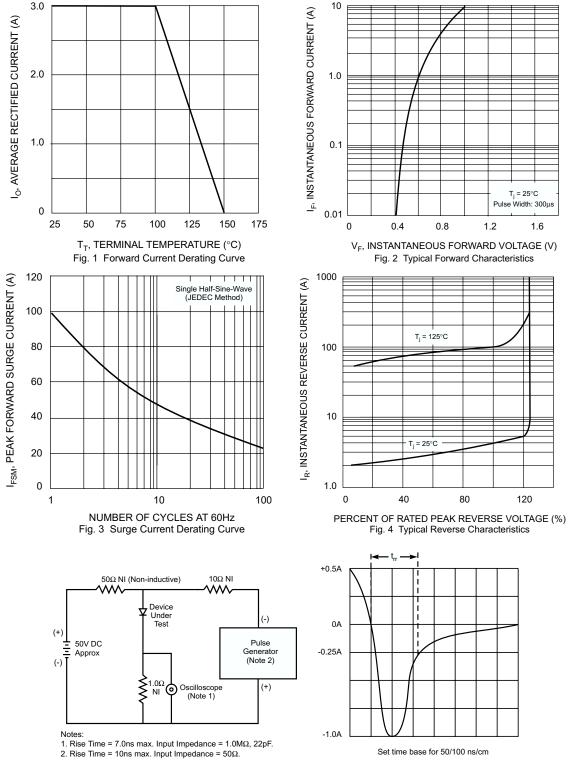


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

